

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Takashi OHSHIMA</td> <td>12/11/2012</td> </tr> <tr> <td>Michio HATANO</td> <td>12/17/2012</td> </tr> <tr> <td>Hideo MORISHITA</td> <td>12/17/2012</td> </tr> </tbody> </table>		Name	Execution Date	Takashi OHSHIMA	12/11/2012	Michio HATANO	12/17/2012	Hideo MORISHITA	12/17/2012
Name	Execution Date								
Takashi OHSHIMA	12/11/2012								
Michio HATANO	12/17/2012								
Hideo MORISHITA	12/17/2012								
RECEIVING PARTY DATA									
Name:	Hitachi High-Technologies Corporation								
Street Address:	24-14, Nishi Shimbashi 1-chome								
City:	Minato-ku, Tokyo								
State/Country:	JAPAN								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13817086</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13817086				
Property Type	Number								
Application Number:	13817086								
CORRESPONDENCE DATA									
Fax Number:	2026288844								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	202-624-2500								
Email:	tyhaynes@crowell.com								
Correspondent Name:	Crowell & Moring LLP								
Address Line 1:	1001 Pennsylvania Avenue, N.W.								
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20004								
ATTORNEY DOCKET NUMBER:	103940.65328US								
NAME OF SUBMITTER:	Michael H. Jacobs								
Total Attachments: 1 source=65328US_Assignment#page1.tif									

OP \$40.00 13817086

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

ELECTRON BEAM APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1)	<u>Takashi Ohshima</u> Takashi OHSHIMA	<u>12/11/2012</u>
2)	<u>Michio Hatano</u> Michio HATANO	<u>12/17/2012</u>
3)	<u>Hideo Morishita</u> Hideo MORISHITA	<u>12/17/2012</u>